

1 Characteristics

Table 2. Absolute maximum ratings (limiting values)

Symbol	Parameter			Value	Unit
$I_{T(RMS)}$	On-state rms current (full sine wave)	TO-220FPAB	$T_c = 105\text{ }^{\circ}\text{C}$	2	A
		DPAK	$T_c = 110\text{ }^{\circ}\text{C}$		
I_{TSM}	Non repetitive surge peak on-state current (full cycle sine wave, T_j initial = $25\text{ }^{\circ}\text{C}$)	F = 60 Hz	t = 16.7 ms	8.4	A
		F = 50 Hz	t = 20 ms	8.0	
I^2t	I^2t Value for fusing	$t_p = 10\text{ ms}$		0.5	A^2s
di/dt	Critical rate of rise of on-state current $I_G = 2 \times I_{GT}$, $t_r = 100\text{ ns}$	F = 120 Hz	$T_j = 125\text{ }^{\circ}\text{C}$	50	$\text{A}/\mu\text{s}$
$V_{PP}^{(1)}$	Non repetitive line peak mains voltage ⁽¹⁾		$T_j = 25\text{ }^{\circ}\text{C}$	2	kV
$P_{G(AV)}$	Average gate power dissipation		$T_j = 125\text{ }^{\circ}\text{C}$	0.1	W
P_{GM}	Peak gate power dissipation ($t_p = 20\text{ }\mu\text{s}$)		$T_j = 125\text{ }^{\circ}\text{C}$	10	W
I_{GM}	Peak gate current ($t_p = 20\text{ }\mu\text{s}$)		$T_j = 125\text{ }^{\circ}\text{C}$	1.6	A
T_{stg} T_j	Storage junction temperature range Operating junction temperature range			-40 to +150 -40 to +125	$^{\circ}\text{C}$
T_l	Maximum lead soldering temperature during 10 s (at 3 mm from plastic case)			260	$^{\circ}\text{C}$
$V_{INS(RMS)}$	Insulation rms voltage		TO-220FPAB	1500	V

1. According to test described in IEC 61000-4-5 standard and [Figure 18](#)

Table 3. Electrical characteristics ($T_j = 25\text{ }^{\circ}\text{C}$, unless otherwise specified)

Symbol	Test conditions	Quadrant		Value	Unit
$I_{GT}^{(1)}$	$V_{OUT} = 12\text{ V}$, $R_L = 33\text{ }\Omega$	I - II - III	MAX	10	mA
V_{GT}	$V_{OUT} = 12\text{ V}$, $R_L = 33\text{ }\Omega$	I - II - III	MAX	1.1	V
V_{GD}	$V_{OUT} = V_{DRM}$, $R_L = 3.3\text{ k}\Omega$, $T_j = 125\text{ }^{\circ}\text{C}$	I - II - III	MIN	0.2	V
$I_H^{(2)}$	$I_{OUT} = 100\text{ mA}$		MAX	10	mA
I_L	$I_G = 1.2 \times I_{GT}$	I - III	MAX	25	mA
		II	MAX	35	
$dV/dt^{(2)}$	$V_{OUT} = 67\% V_{DRM}$ gate open, $T_j = 125\text{ }^{\circ}\text{C}$		MIN	500	$\text{V}/\mu\text{s}$
$(di/dt)_c^{(2)}$	$(dV/dt)_c = 15\text{ V}/\mu\text{s}$, $T_j = 125\text{ }^{\circ}\text{C}$		MIN	0.5	A/ms
V_{CL}	$I_{CL} = 0.1\text{ mA}$, $t_p = 1\text{ ms}$, $T_j = 25\text{ }^{\circ}\text{C}$		MIN	850	V

1. Minimum I_{GT} is guaranteed at 5% of I_{GT} max

2. For both polarities of OUT pin referenced to COM pin

Table 4. Static electrical characteristics

Symbol	Test conditions			Value	Unit
$V_{TM}^{(1)}$	$I_{TM} = 2.8 \text{ A}$, $t_p = 500 \mu\text{s}$	$T_j = 25 \text{ }^\circ\text{C}$	MAX	2	V
$V_{TO}^{(1)}$	Threshold voltage	$T_j = 125 \text{ }^\circ\text{C}$	MAX	0.9	V
$R_D^{(1)}$	Dynamic resistance	$T_j = 125 \text{ }^\circ\text{C}$	MAX	250	m Ω
I_{DRM} I_{RRM}	$V_{OUT} = V_{DRM} / V_{RRM}$	$T_j = 25 \text{ }^\circ\text{C}$	MAX	10	μA
		$T_j = 125 \text{ }^\circ\text{C}$		0.5	mA

1. For both polarities of OUT pin referenced to COM pin

Table 5. Thermal resistances

Symbol	Parameter		Value	Unit
$R_{th(j-c)}$	Junction to case (AC)	DAK	4.5	$^\circ\text{C/W}$
		TO-220FPAB	7	
$R_{th(j-a)}$	Junction to ambient	TO-220FPAB	60	
		$S_{CU}^{(1)} = 0.5 \text{ cm}^2$ DAK	70	

1. S_{CU} = copper surface under tab

Figure 2. Maximum power dissipation versus on-state rms current (full cycle)

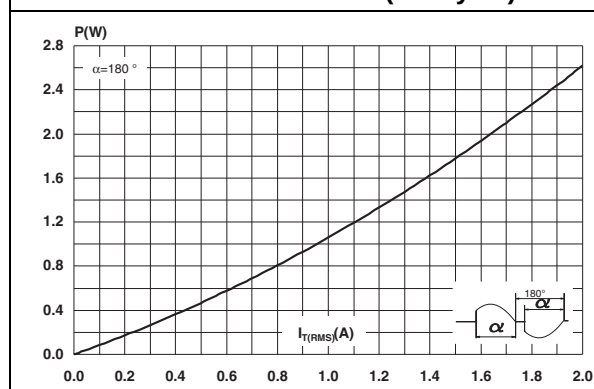


Figure 3. On-state rms current versus case temperature

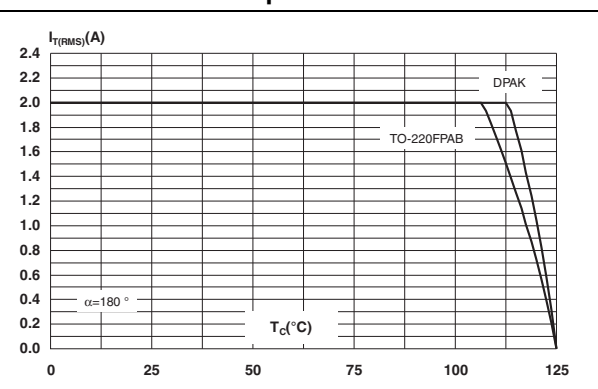


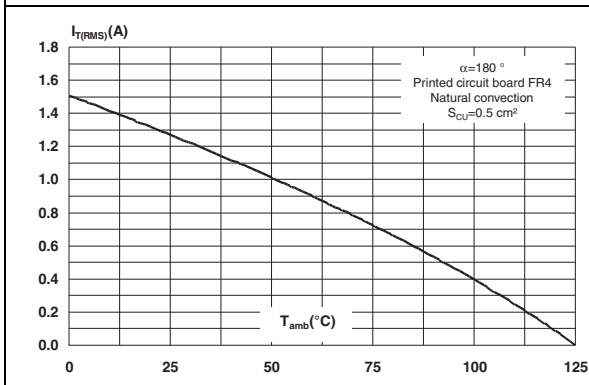
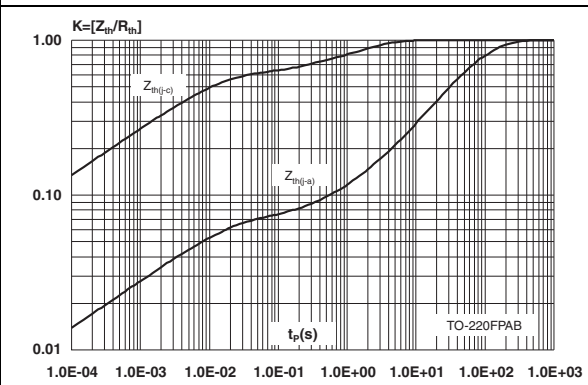
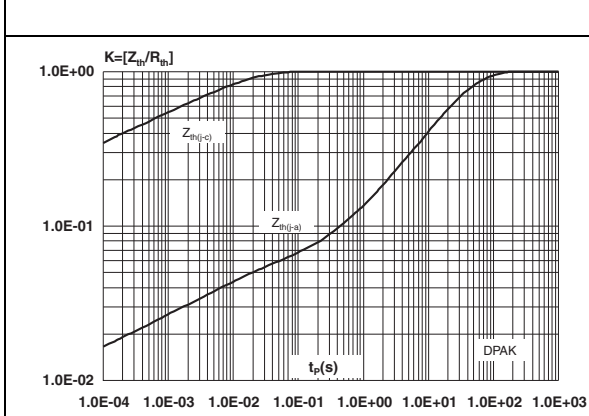
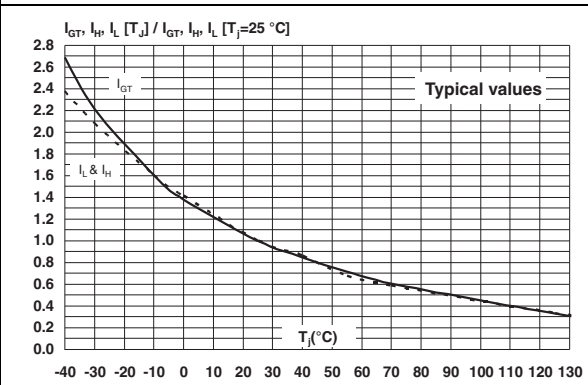
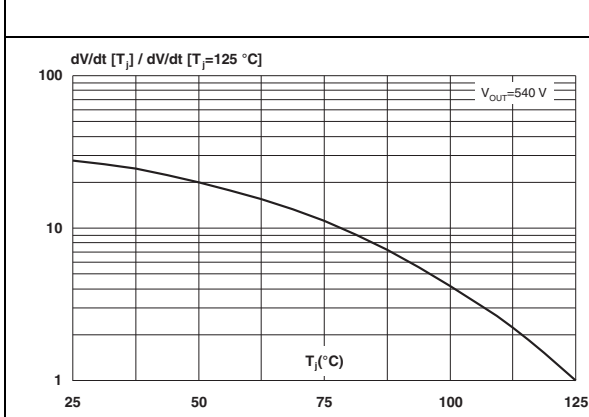
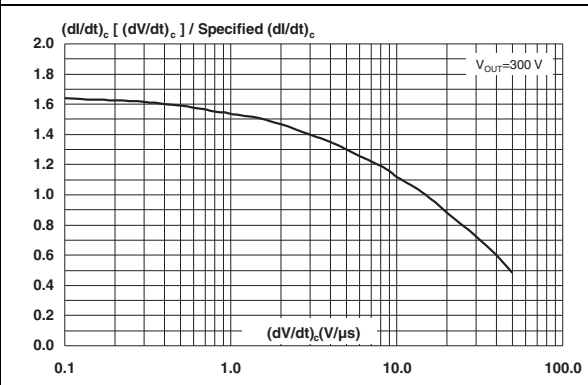
Figure 4. On-state rms current versus ambient temperature**Figure 5. Relative variation of thermal impedance versus pulse duration TO-220FPAB****Figure 6. Relative variation of thermal impedance versus pulse duration DPAK****Figure 7. Relative variation of gate trigger, holding and latching current versus junction temperature****Figure 8. Relative variation of static dV/dt versus junction temperature****Figure 9. Relative variation of critical rate of decrease of main current versus reapplied dV/dt (typical values)**

Figure 10. Relative variation of critical rate of decrease of main current versus junction temperature

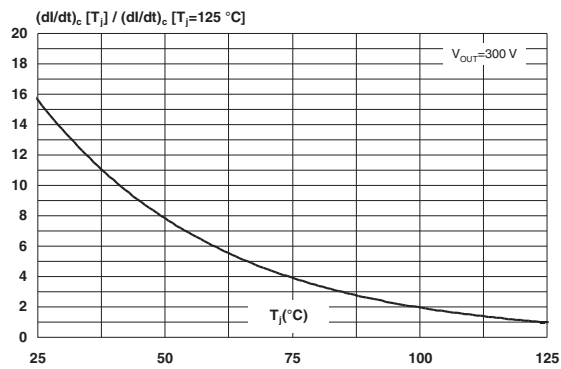


Figure 11. Surge peak on-state current versus number of cycles

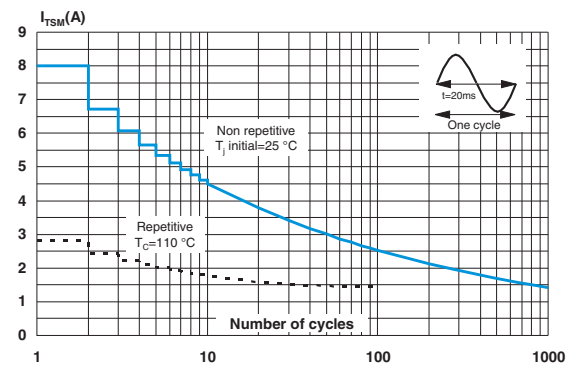


Figure 12. Non repetitive surge peak on-state current and corresponding value of I^2t

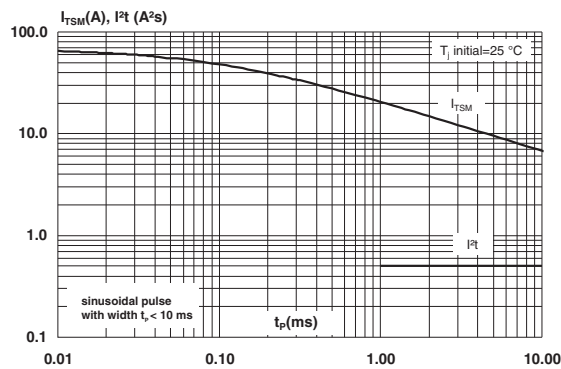


Figure 13. On-state characteristics (maximum values)

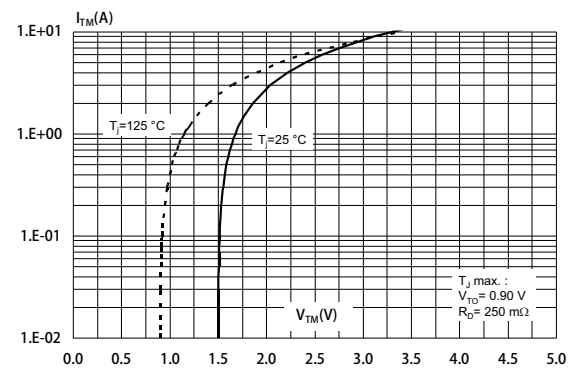


Figure 14. Thermal resistance junction to ambient versus copper surface under tab DPAK

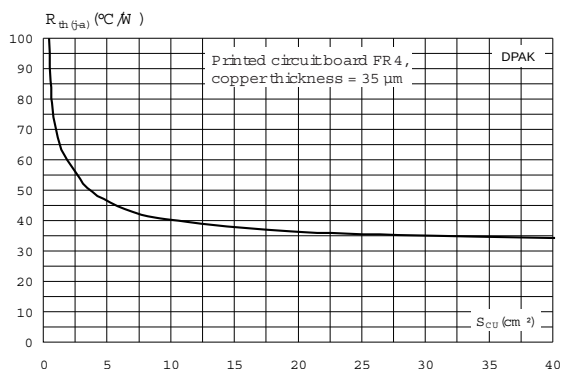
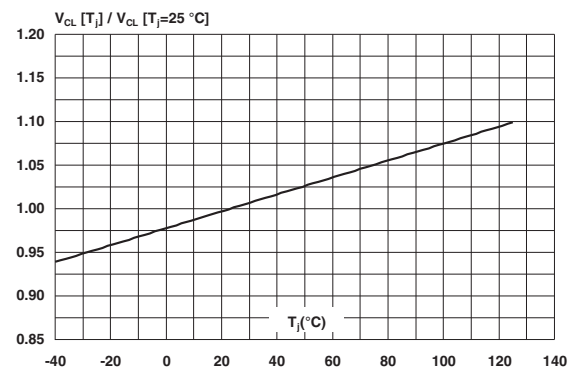


Figure 15. Relative variation of clamping voltage V_{CL} versus junction temperature

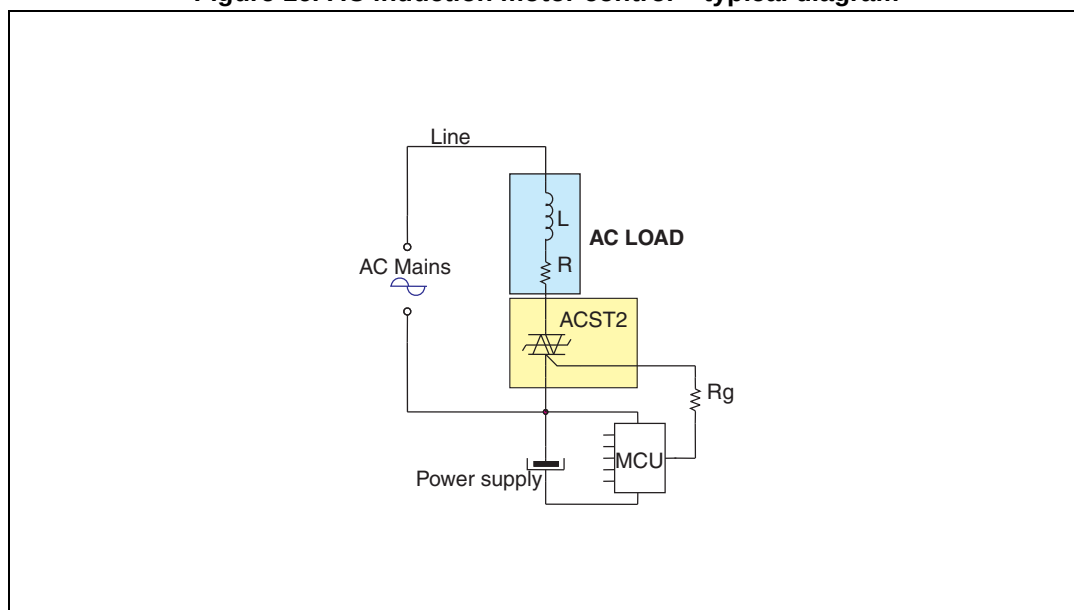


2 Application information

2.1 Typical application description

The ACST2 device has been designed to switch on and off highly inductive or resistive loads such as pump, valve, fan, or bulb lamp. Thanks to its high sensitivity ($I_{GT} \text{ max} = 10 \text{ mA}$), the ACST2 can be driven directly by logic level circuits through a resistor as shown on the typical application diagram. Thanks to its thermal and turn-off commutation performances, the ACST2 switch can drive, without any additional snubber, an inductive load up to 2 A.

Figure 16. AC induction motor control – typical diagram



2.2 AC line transient voltage ruggedness

In comparison with standard Triacs, which are not robust against surge voltage, the ACST2 is self-protected against over-voltage, specified by the new parameter V_{CL} . In addition, the ACST2 is a sensitive device ($I_{GT} = 10 \text{ mA}$), but provides a high noise immunity level against fast transients. The ACST2 switch can safely withstand AC line transient voltages either by clamping the low energy spikes, such as inductive spikes at switch off, or by switching to the on state (for less than 10 ms) to dissipate higher energy shocks through the load. This safety feature works even with high turn-on current ramp up.

The test circuit of [Figure 17](#) represents the ACST2 application, and is used to stress the ACST switch according to the IEC 61000-4-5 standard conditions. With the additional effect of the load which is limiting the current, the ACST switch withstands the voltage spikes up to 2 kV on top of the peak line voltage. The protection is based on an overvoltage crowbar technology. The ACST2 folds back safely to the on state as shown in [Figure 18](#). The ACST2 recovers its blocking voltage capability after the surge and the next zero current crossing. Such a non repetitive test can be done at least 10 times on each AC line voltage polarity.

Figure 17. Overvoltage ruggedness test circuit for resistive and inductive loads for IEC 61000-4-5 standards

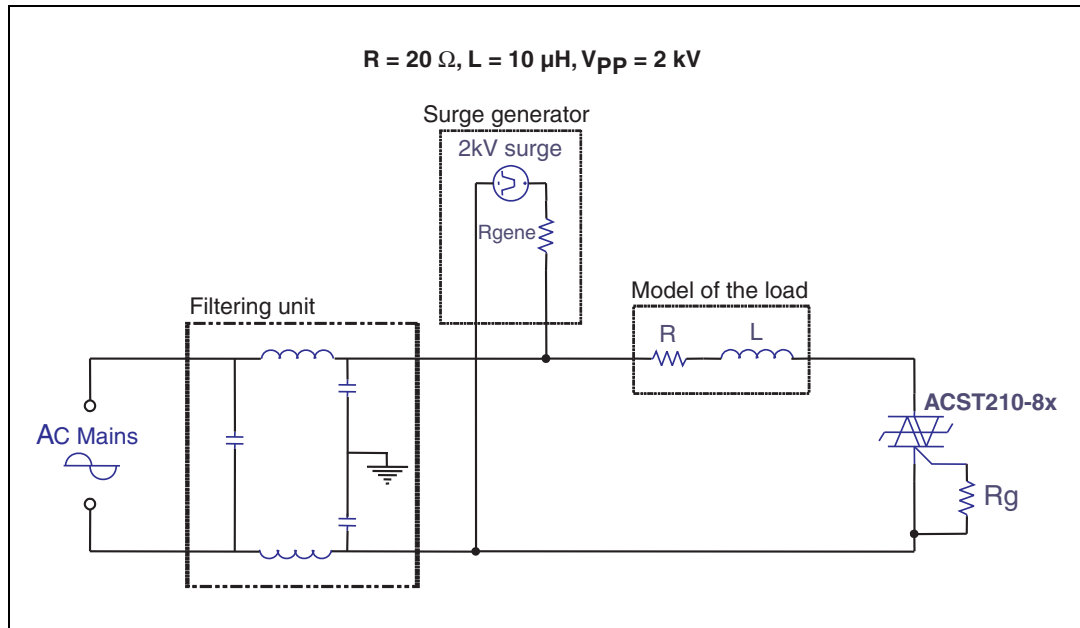
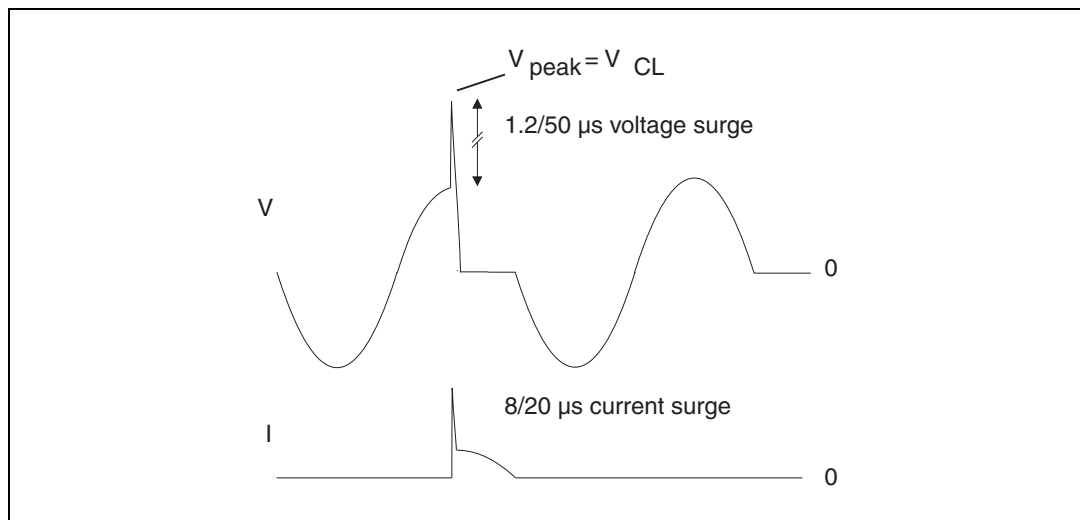


Figure 18. Typical current and voltage waveforms across the ACST2 during IEC 61000-4-5 standard test



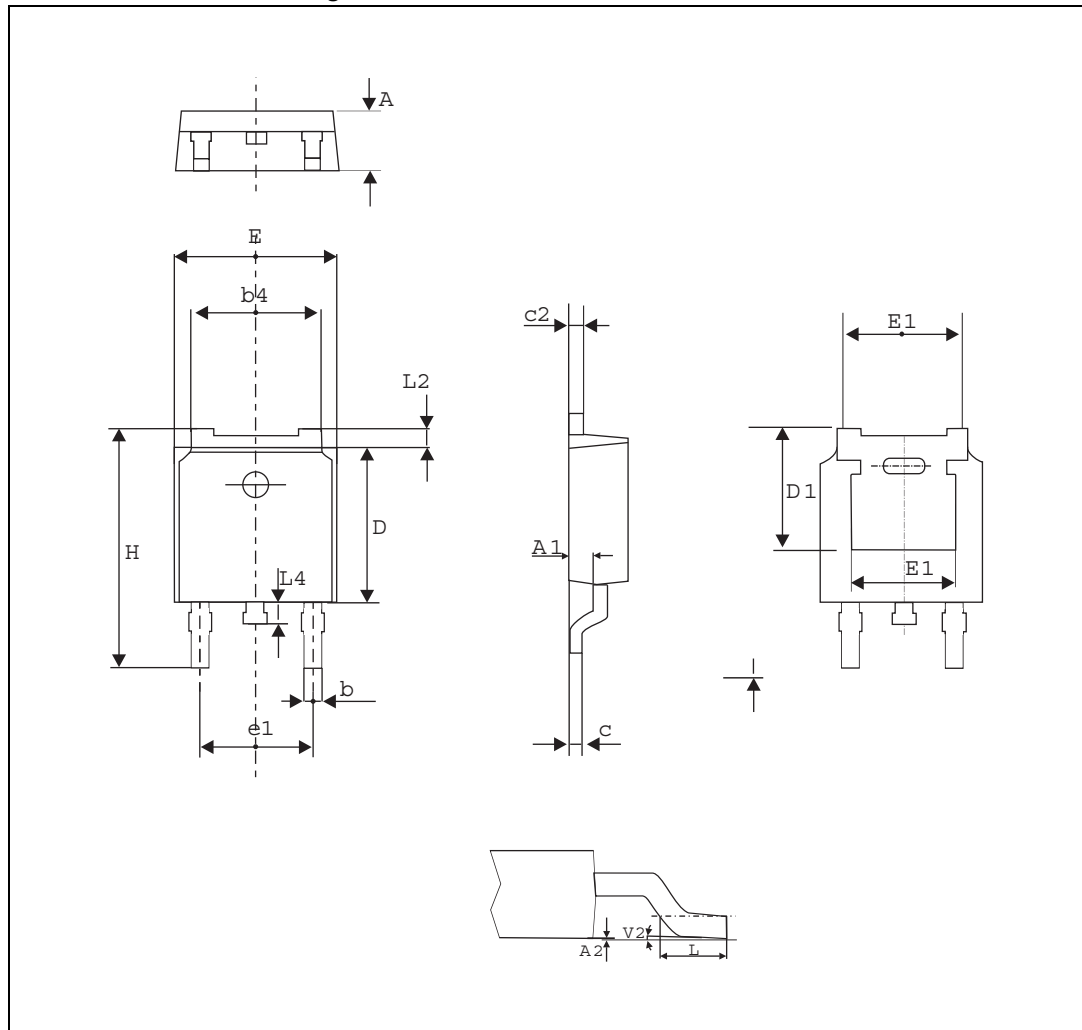
2.3 Electrical noise immunity

The ACST2 is a sensitive device ($I_{GT} = 10\ \text{mA}$) and can be controlled directly through a simple resistor by a logic level circuit, and still provides a high electrical noise immunity. The intrinsic immunity of the ACST2 is shown by the specified dV/dt equal to $500\ \text{V}/\mu\text{s}$ @ $125\ ^\circ\text{C}$. This immunity level is 5 to 10 times higher than the immunity provided by an equivalent standard technology Triac with the same sensitivity. In other words, the ACST2 is sensitive, but has an immunity usually available only for non-sensitive device (I_{GT} higher than $35\ \text{mA}$).

Table 6. TO-220FPAB dimension values

Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	4.4		4.6	0.173		0.181
B	2.5		2.7	0.098		0.106
D	2.5		2.75	0.098		0.108
E	0.45		0.70	0.018		0.027
F	0.75		1	0.030		0.039
F1	1.15		1.70	0.045		0.067
F2	1.15		1.70	0.045		0.067
G	4.95		5.20	0.195		0.205
G1	2.4		2.7	0.094		0.106
H	10		10.4	0.393		0.409
L2		16			0.63	
L3	28.6		30.6	1.126		1.205
L4	9.8		10.6	0.386		0.417
L5	2.9		3.6	0.114		0.142
L6	15.9		16.4	0.626		0.646
L7	9.00		9.30	0.354		0.366
Dia.	3.00		3.20	0.118		0.126

Figure 20. DPAK dimension definitions

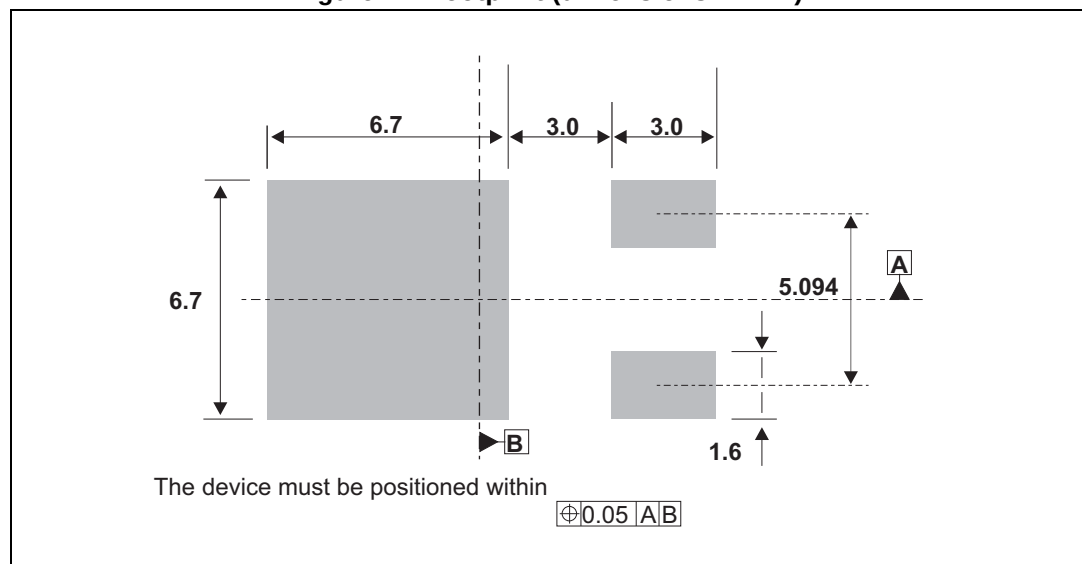


Note: *this package drawing may slightly differ from the physical package. However, all the specified dimensions are guaranteed.*

Table 7. DPAK dimension values

Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	2.18		2.40	0.086		0.094
A1	0.90		1.10	0.035		0.043
A2	0.03		0.23	0.001		0.009
b	0.64		0.90	0.025		0.035
b4	4.95		5.46	0.195		0.215
c	0.46		0.61	0.018		0.024
c2	0.46		0.60	0.018		0.023
D	5.97		6.22	0.235		0.244
D1	5.10			0.201		
E	6.35		6.73	0.250		0.264
E1		4.32			0.170	
e1	4.40		4.70	0.173		0.185
H	9.35		10.40	0.368		0.409
L	1.00		1.78	0.039		0.070
L2			1.27			0.05
L4	0.60		1.02	0.023		0.040
V2	0°		8°	0°		8°

Figure 21. Footprint (dimensions in mm)



4 Ordering information

Figure 22. Ordering information scheme

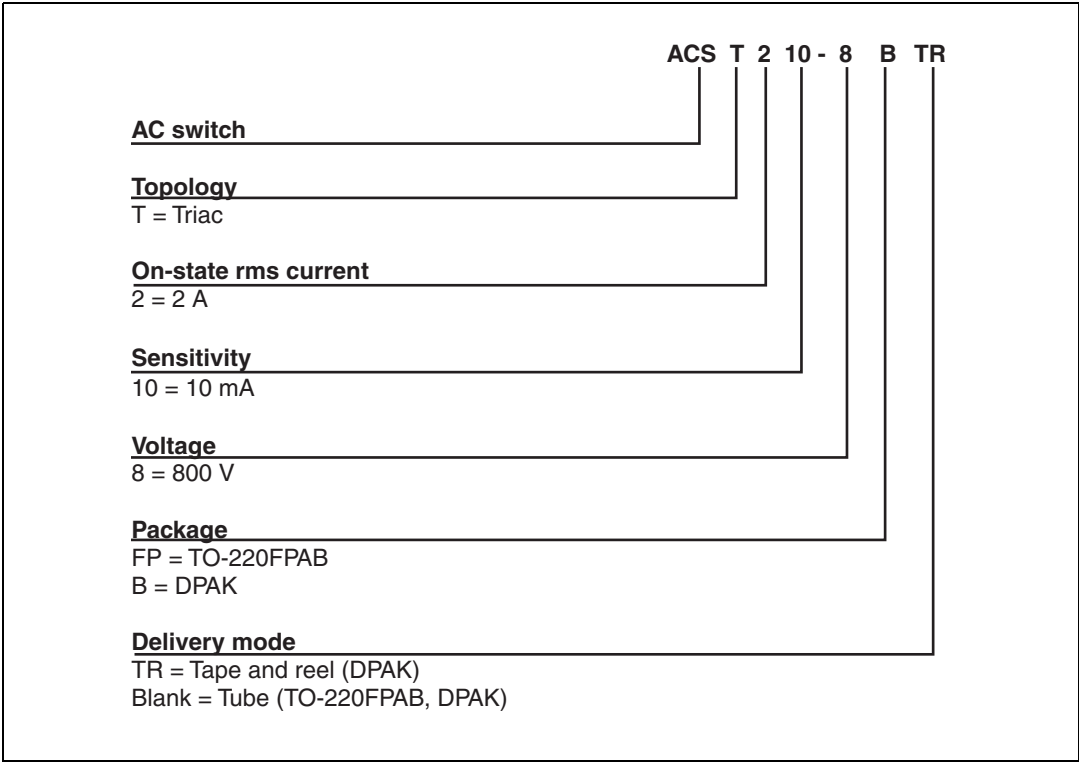


Table 8. Ordering information

Order code	Marking	Package	Weight	Base Qty	Packing mode
ACST210-8FP	ACST2108	TO-220FPAB	2.4g	50	Tube
ACST210-8B		DPAK	0.3g	50	Tube
ACST210-8B-TR		DPAK	0.3g	2500	Tape and Reel

5 Revision history

Table 9. Document revision history

Date	Revision	Changes
01-Mar-2007	1	Initial release.
13-Apr-2010	2	Updated ECOPACK statement. Reformatted for consistency with other datasheets in this product class.
01-Jul-2010	3	Updated Figure 22 .
24-May-2014	4	Updated DPAK package information and reformatted to current standard.

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